BT139 series

Triacs

Rev. 04.00 — 6 July 2004

Product data sheet

1. Product profile

1.1 General description

Passivated triacs in a SOT78 plastic package. intended for use in applications requiring high bidirectional transient and blocking voltage capability.

1.2 Features

High thermal cycling performance.

1.3 Applications

Motor control

Industrial and domestic lighting, heating and static switching.

1.4 Quick reference data

- $V_{DRM} \le 600 \text{ V (BT139-600)}$
- V_{DRM} ≤ 600 V (BT139-600F)
- $V_{DRM} \le 800 \text{ V (BT139-800)}$
- V_{DRM} ≤ 800 V (BT139-800F)
- V_{DRM} ≤ 800 V (BT139-800G)
- $I_{T(RMS)} \le 16 A$
- $I_{TSM} \le 155 A.$

2. Pinning information

Table 1: Discrete pinning

Pin	Description	Simplified outline	Symbol
1	main terminal 1		N 1
2	main terminal 2	mb	T2—T1
3	gate	205	`G sym051
mb	main terminal 2	1 2 3	
		SOT78 (TO-220AB)	





3. Ordering information

Table 2: Ordering information

Type number	Package	Package						
	Name	Description	Version					
BT139-600	TO-220AB	plastic single-ended package; heatsink mounted; 1 mounting hole;	SOT78					
BT139-600F		3-lead TO-220AB						
BT139-800								
BT139-800F								
BT139-800G								

4. Limiting values

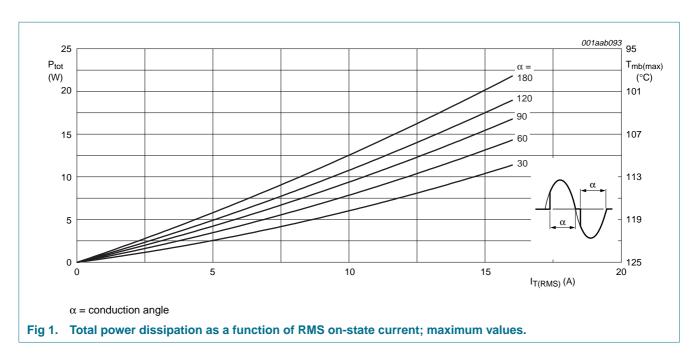
Table 3: Limiting values

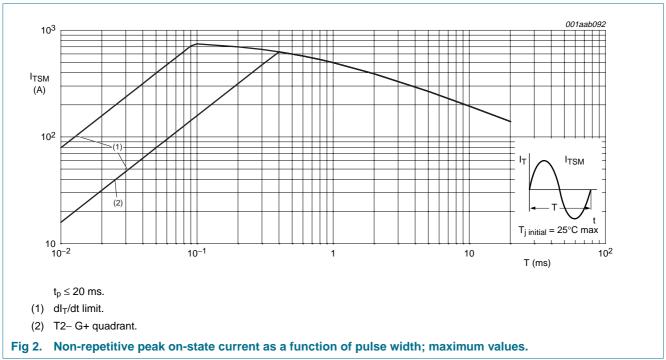
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage				
	BT139-600		-	600 <u>[1]</u>	V
	BT139-800		-	800	V
I _{T(RMS)}	RMS on-state current	full sine wave; T _{mb} ≤ 99 °C; Figure 4 and Figure 5	-	16	Α
I _{TSM}	non-repetitive peak on-state current	full sine wave; T _j = 25 °C prior to surge; <u>Figure 2</u> and <u>Figure 3</u>			
		t = 20 ms	-	155	Α
		t = 16.7 ms	-	170	Α
l ² t	I ² t for fusing	t = 10 ms	-	120	A ² s
dl _T /d _t	repetitive rate of rise of on-state current after triggering	$I_{TM} = 20 \text{ A}; I_G = 0.2 \text{ A};$ $dI_G/dt = 0.2 \text{ A}/\mu\text{s}$			
		T2+ G+	-	50	A/μs
		T2+ G-	-	50	A/μs
		T2- G-	-	50	A/μs
		T2- G+	-	10	A/μs
I _{GM}	peak gate current		-	2	Α
V _{GM}	peak gate voltage		-	5	V
P _{GM}	peak gate power		-	5	W
P _{G(AV)}	average gate power	over any 20 ms period	-	0.5	W
T _{stg}	storage temperature		-40	+150	°C
T _j	junction temperature		-	125	°C

^[1] Although not recommended, off-state voltages up to 800 V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 15 A/µs.

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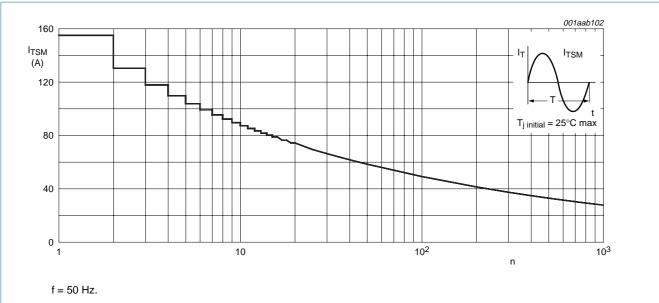


Fig 3. Non-repetitive peak on-state current as a function of number of sinusoidal current cycles; maximum values.

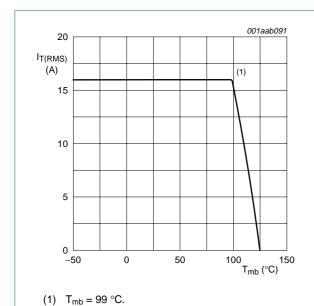
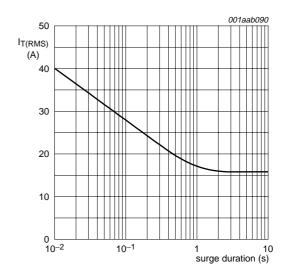


Fig 4. RMS on-state current as a function of mounting base temperature; maximum values.



f = 50 Hz; $T_{mb} \leq 99~^{\circ}C.$

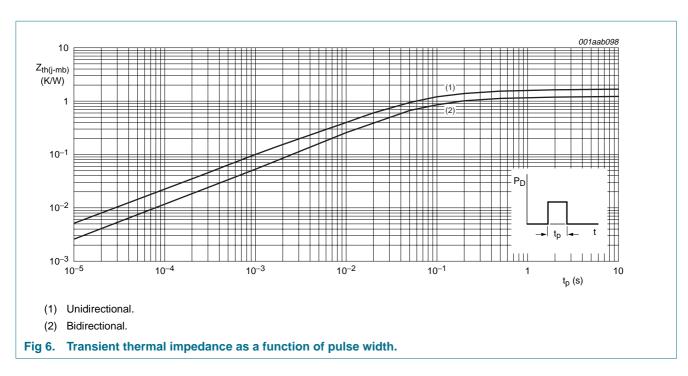
Fig 5. RMS on-state current as a function of surge duration; maximum values.

5. Thermal characteristics

Table 4: Thermal characteristics

Symbol	Parameter	Conditions	Тур	Max	Unit
R _{th(j-mb)}	thermal resistance junction to	full cycle Figure 6	-	1.2	K/W
	mounting base	half cycle Figure 6	-	1.7	K/W
R _{th(j-a)}	thermal resistance junction to ambient	in free air	60	-	K/W

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6. Static characteristics

Table 5: Static characteristics $T_i = 25 \,^{\circ}C$ unless otherwise stated.

Symbol	Parameter	Conditions		BT139)		BT139-F		BT139-G			Unit
			Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	_
I _{GT}	gate trigger current	$V_D = 12 V;$ $I_T = 0.1 A;$ Figure 8										
		T2+ G+	-	5	35	-	5	25	-	5	50	mA
		T2+ G-	-	8	35	-	8	25	-	8	50	mA
		T2- G-	-	10	35	-	10	25	-	10	50	mA
		T2- G+	-	22	70	-	22	70	-	22	100	mA
IL	latching current	$V_D = 12 V;$ $I_{GT} = 0.1 A;$ <u>Figure 9</u>										
		T2+ G+	-	7	40	-	7	40	-	7	60	mΑ
		T2+ G-	-	20	60	-	20	60	-	20	90	mΑ
		T2- G-	-	8	40	-	8	40	-	8	60	mA
		T2- G+	-	10	60	-	10	60	-	10	90	mA
I _H	holding current	$V_D = 12 V;$ $I_{GT} = 0.1 A;$ Figure 10	-	6	45	-	6	45	-	6	60	mA
V _T	on-state voltage	I _T = 20 A; <u>Figure 11</u>	-	1.2	1.6	-	1.2	1.6	-	1.2	1.6	V



 Table 5:
 Static characteristics ...continued

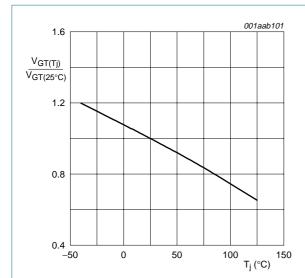
 $T_i = 25 \,^{\circ}C$ unless otherwise stated.

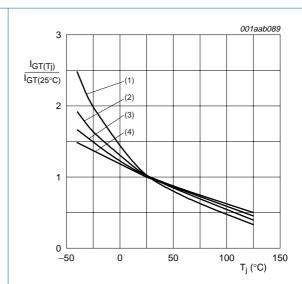
Symbol	Parameter	Conditions		BT139)	E	3T139-	F	E	3T139-	G	Unit
			Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
V _{GT}	gate trigger voltage	$V_D = 12 V;$ $I_T = 0.1 A;$ Figure 7	-	0.7	1.5	-	0.7	1.5	-	0.7	1.5	V
		$V_D = 400 \text{ V};$ $I_T = 0.1 \text{ A};$ $T_j = 125 \text{ °C}$	0.25	0.4	-	0.25	0.4	-	0.25	0.4	-	V
I _D	off-state leakage current	$V_D = V_{DRM(max)};$ $T_j = 125 ^{\circ}C$	-	0.1	0.5	-	0.1	0.5	-	0.1	0.5	mA

7. Dynamic characteristics

Table 6: Dynamic characteristics

Symbol	Parameter	Conditions		BT139		ı	BT139-F			BT139-G		
			Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
dV _D /dt	critical rate of rise of off-state voltage	$V_{DM} = 67 \%$ $V_{DRM(max)}$; $T_j = 125 ^{\circ}C$; exponential waveform; gate open circuit	200	250	-	50	250	-	200	250	-	V/μs
dV _{com} /dt	critical rate of change of commutating voltage	$\begin{split} &V_{DM} = 400 \text{ V}; \\ &T_j = 95 \text{ °C}; \\ &I_{T(RMS)} = 16 \text{ A}; \\ &dI_{com}/dt = 7.2 \text{ A/ms}; \\ &gate \text{ open circuit} \end{split}$	10	20	-	-	20	-	10	20	-	V/µs
t _{gt}	gate controlled turn-on time	$\begin{split} I_{TM} &= 20 \text{ A;} \\ V_D &= V_{DRM(max)}; \\ I_G &= 0.1 \text{ A;} \\ dI_G/dt &= 5 \text{ A}/\mu\text{s} \end{split}$		2	-	-	2	-		2	-	μs





- (1) T2+ G+.
- (2) T2-G-.
- (3) T2- G-.
- (4) T2-G+.

Fig 7. Normalized gate trigger voltage as a function of junction temperature.

Fig 8. Normalized gate trigger current as a function of junction temperature.

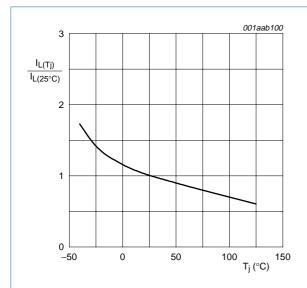


Fig 9. Normalized latching current as a function of junction temperature.

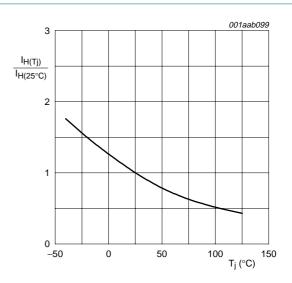
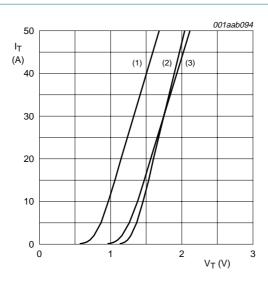


Fig 10. Normalized holding current as a function of junction temperature.

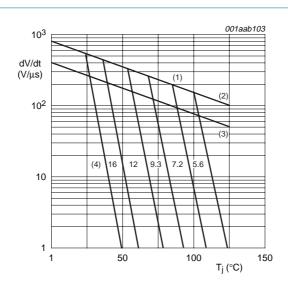


 $V_0 = 1.06 \text{ V}.$

 $R_S = 0.0304 \ \Omega.$

- (1) $T_i = 125$ °C; typical values.
- (2) $T_i = 25$ °C; maximum values.
- (3) $T_i = 125 \,^{\circ}C$; maximum values.

Fig 11. On-state current characteristics.



The triac should commutate when the $dI_{\overline{1}}/dt$ is below the value on the appropriate curve for pre-commutation $dI_{\overline{1}}/dt$.

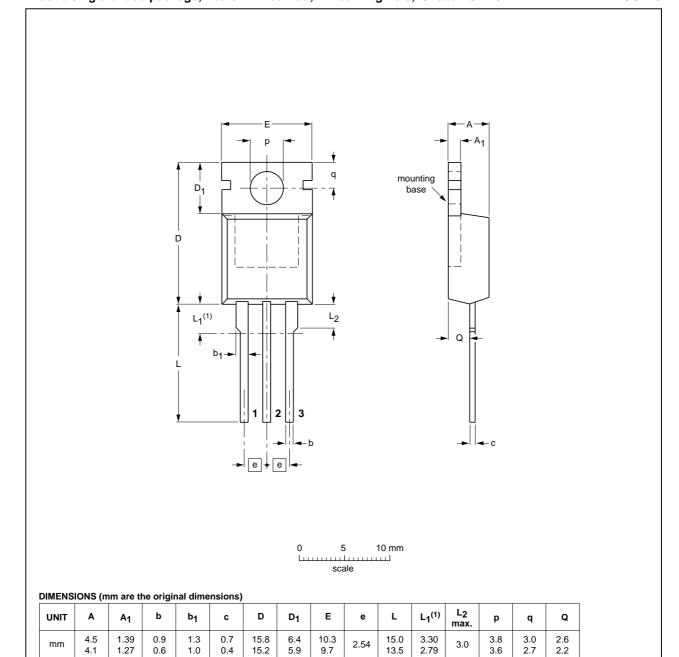
- (1) BT139 SERIES.
- (2) BT139...G SERIES.
- (3) BT139...F SERIES.
- (4) $dI_{com}/dt = 20 \text{ A/ms}.$

Fig 12. Critical rate of change of commutating voltage as a function of junction temperature; minimum values.

8. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB

SOT78



Note

1. Terminals in this zone are not tinned.

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA	PROJECTION		
SOT78		3-lead TO-220AB	SC-46		01-02-16 03-01-22	

Fig 13. Package outline.

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9. Revision history

Table 7: Revision history

Document ID	Release date	Data sheet status	Change notice	Order number	Supersedes
BT139_SERIES_4	20040706	Product data sheet	-	9397 750 13358	BT139_SERIES_3
Modifications:	Data sheet upo	lated to latest standards.			
BT139_SERIES_3	20030401	Product specification	-	-	BT139_SERIES_2
BT139_SERIES_2	20010701	Product specification	-	-	BT139_SERIES_1
BT139_SERIES_1	19970901	Product specification	-	-	-



Level	Data sheet status [1]	Product status [2] [3]	Definition
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14. Contents

1	Product profile
1.1	General description
1.2	Features
1.3	Applications 1
1.4	Quick reference data 1
2	Pinning information 1
3	Ordering information 2
4	Limiting values
5	Thermal characteristics 3
6	Static characteristics 3
7	Dynamic characteristics 4
8	Package outline 9
9	Revision history 10
10	Data sheet status11
11	Definitions
12	Disclaimers
13	Contact information11



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